

AMENDMENST TO THE CLAIMS

1.-7. (Canceled)

8. (Currently Amended) An apparatus, comprising:

a heat spreader comprising heat conductive material and a ~~non-contiguous~~contiguous wall structure extending from a surface of the heat spreader; and

a package substrate;

~~a flexible material coupled to the wall structure in contact with surface of the heat spreader and to couple to the package substrate, the flexible material defining a perimeter of a cavity; and~~

a circuit substrate disposed within the cavity.

9. (Previously Presented) The apparatus of claim 8, wherein the flexible material comprises polymeric sealant material.

10. (Previously Presented) The apparatus of claim 8, wherein the heat spreader is plated with nickel.

11. (Previously Presented) The apparatus of claim 8, wherein the heat spreader is coated with a heat-conductive organic material.

12.-17. (Canceled)

18. (Currently Amended) A semiconductor package, comprising:

a substrate having a top-surface;

at least one semiconductor device coupled to the top-surface of the substrate; and

a cover coupled to the top-surface of the substrate through a flexible sealant material, the flexible material contacting a surface of the cover and the surface of the substrate and creating a space between the substrate and the cover, the semiconductor device residing within the space, and the cover comprised of a heat-conductive material; and

a thermal interface material comprising metal particles disposed between a surface of the semiconductor device and the surface of the cover,

~~wherein the cover comprises a plurality of mechanical contiguous attachment structures structure extending from a the surface thereof and the coupling of the cover to the top surface of the substrate comprises coupling the plurality of mechanical attachment structures to the surface of the substrate into the flexible material.~~

19. (Original) The semiconductor package of claim 18, wherein the cover is a heat spreader.

20.-23. (Canceled)

24. (New) The apparatus of claim 8 further comprising:

a thermal interface material comprising metal particles disposed between a surface of the circuit substrate and the surface of the heat spreader.